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Advisory Action	Application No.	Applicant(s)	
	10/076,355	YAMASHITA, TOMIO	
	Examiner	Art Unit	
	Hung K. Vu	2811	
The MAILING DATE of this communication app	pears on the cover sheet with the	correspondence add	ress
THE REPLY FILED 01 October 2003 FAILS TO PLAC Therefore, further action by the applicant is required to final rejection under 37 CFR 1.113 may only be either: condition for allowance; (2) a timely filed Notice of App Examination (RCE) in compliance with 37 CFR 1.114.	avoid abandonment of this appli (1) a timely filed amendment wh	cation. A proper relich places the appli	ply to a cation in
PERIOD FOR R	EPLY [check either a) or b)]		
a) The period for reply expires 3_months from the mailing date b) The period for reply expires on: (1) the mailing date of this A- event, however, will the statutory period for reply expire later ONLY CHECK THIS BOX WHEN THE FIRST REPLY WA 706.07(f). Extensions of time may be obtained under 37 CFR 1.136(a). The chave been filed is the date for purposes of determining the period of exte 37 CFR 1.17(a) is calculated from: (1) the expiration date of the shorten (b) above, if checked. Any reply received by the Office later than three rearned patent term adjustment. See 37 CFR 1.704(b).	dvisory Action, or (2) the date set forth in the than SIX MONTHS from the mailing date of S FILED WITHIN TWO MONTHS OF THE date on which the petition under 37 CFR 1, ension and the corresponding amount of the d statutory period for reply originally set in	of the final rejection. IE FINAL REJECTION. 136(a) and the appropriate execution to the final Office action; or	See MPEP e extension fee tension fee under (2) as set forth in
1. A Notice of Appeal was filed on Appellan 37 CFR 1.192(a), or any extension thereof (37 C			
2. \boxtimes The proposed amendment(s) will not be entered	because:		
(a) M they raise new issues that would require furt	her consideration and/or search	(see NOTE below);	
(b) they raise the issue of new matter (see Note	e below);		
(c) they are not deemed to place the application issues for appeal; and/or	n in better form for appeal by ma	terially reducing or	simplifying the
(d) they present additional claims without canc	eling a corresponding number of	finally rejected clai	ms.
NOTE: See Continuation Sheet.			
3. Applicant's reply has overcome the following reju	ection(s):		
4. Newly proposed or amended claim(s) wou canceling the non-allowable claim(s).	ld be allowable if submitted in a	separate, timely file	d amendment
5. ☑ The a) ☐ affidavit, b) ☐ exhibit, or c) ☑ request application in condition for allowance because:		nsidered but does No	OT place the
6. The affidavit or exhibit will NOT be considered by raised by the Examiner in the final rejection.	ecause it is not directed SOLEL'	Y to issues which we	ere newly
7. For purposes of Appeal, the proposed amendme explanation of how the new or amended claims			and an
The status of the claim(s) is (or will be) as follow	S:		
Claim(s) allowed:			
Claim(s) objected to:			
Claim(s) rejected: <u>1,2,4,6-10 and 12-14</u> .			
Claim(s) withdrawn from consideration:			
8. The proposed drawing correction filed on	is a)□ approved or b)□ disar	oproved by the Exar	miner.
9. Note the attached Information Disclosure Statem	nent(s)(PTO-1449) Paper No(s).	·	
10. Other:		Hung Un	

Hungler HUNG VU PATENT EXAMINER Continuation Sheet (PTOL-303) 110/076,355

Application No.

Continuation of 2. NOTE: Extensive amendments to Claim 12 raise new issues that would require further consideration and/or search.

Continuation of 5. does NOT place the application in condition for allowance because: The specification does not disclose a lower wiring layer having an opening, conductive portion filling the opening and at least one dielectric member embedded in the conductive portion nor disclose an upper wiring layer having an upper opening, an upper conductive portion filling the upper opening and at least one dielectric member embedded in the upper conductive portion, as recited in Claims 1 and 6. Applicant asserts that the specification disclose the claimed invention. This argument is not convincing because the specification only discloses the lower wiring layer is the combination of the dielectric layer (10) and the pad (11) and the upper wiring layer is the combination of the dielectric layer (30) and the pad (31). There is no disclosure of the wiring layer having an opening, conductive portion filling the opening and at least one dielectric member embedded in the conductive portion. Since the wiring layer is the combination of the dielectric and the pad, the only place where the opening would be is where the dielectric member (11i or 31i) located. As a result, a lower wiring layer has an opening in which a first dielectric member (11i) filling the opening, and an upper wiring layer has an upper opening in which a second dielectric member (31i) filling the upper opening. There is no conductive portion filling the opening because the first dielectric member (11i) is already filled the upper opening.